



## **Microcross Components Acquires RTI International's Microsystem Integration and Packaging (MIP) Group**

**ORLANDO, Florida, October 5, 2016** – Microcross Components, Inc. (“Microcross”) headquartered in Orlando, Florida is pleased to announce the strategic acquisition of RTI International’s Microsystem Integration and Packaging (“MIP”) Group, one of the premier wafer bumping and wafer level packaging research and fabrication facilities in the United States, servicing commercial and government clients, situated in Research Triangle Park, North Carolina.

The merger brings together MIP’s value-added semiconductor processing techniques, including wafer bumping, 2.5D/3D packaging and interconnects plus novel sensor and thermal management devices, with the global hi-reliability electronics platform of Microcross Components.

“By combining the expertise and competencies of MIP and Microcross, Microcross will further expand its capabilities to serve customers in the defense and medical electronics sectors with advanced packaging needs – particularly those with custom processing needs or whose products are subject to export controls. Concurrently, RTI International’s seasoned MIP team (henceforward to be named the “Advanced Interconnect Technology” Group), led by Dr. John Lannon, will be able to leverage the global sales network and wafer supply partnerships Microcross has developed. Additionally, MIP can now offer its package solutions in conjunction with other Microcross advanced service divisions, such as STS in Milpitas. This is an exciting strategic opportunity for both organizations,” stated Richard Kingdon, CEO of Microcross Components.

“For some time we have been thinking about the future growth of our Electronics and Applied Physics Division, which provides value-added semiconductor processing services for government and commercial clients,” advised RTI International President & CEO Wayne Holden, Ph.D. “This merger supports RTI’s long-term strategy, will stimulate faster growth for the MIP operation and will allow MIP to better capitalize on the opportunities that exist in the US defense and medical electronics industries.”

### **About Microcross Components, Inc.**

[Microcross](#) is a leading one-source, one-solution provider of Bare Die and Wafers, Custom Packaging and Assembly, Component Modification Services, Electrical and Environmental Testing and Standard Products to manufacturers and users of semiconductor devices. In business for more than 35 years, our comprehensive array of high-reliability capabilities serve the global Defense, Space, Medical, Industrial, and Fabless Semiconductor markets. Microcross possesses the sourcing, assembly, test and logistics expertise needed to support an application throughout its entire program cycle.

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**About RTI International**

[RTI International](#) is an independent, nonprofit research institute that provides research, development and technical services to government and commercial clients worldwide. The Microsystem Integration and Packaging Group provide value-added semiconductor processing services for government and commercial clients. These services include wafer-level packaging, 2.5D/3D packaging and interconnects and novel sensor and thermal management devices.